

Stock Code: 688416



Zbit Semiconductor, Inc.

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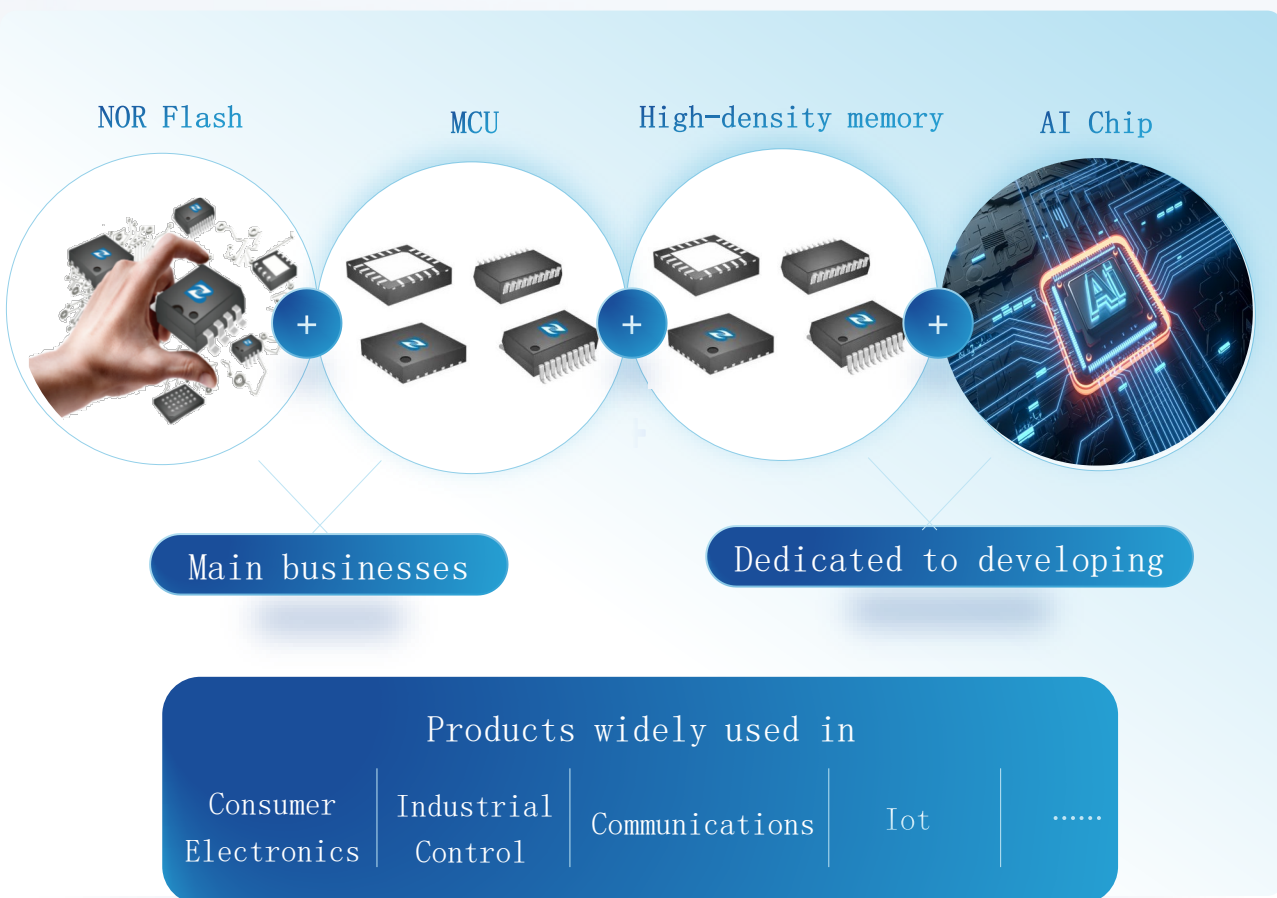
PROFILE

PART 01





Founded in 2015, our company is a leading chip design firm in the industry.
On August 29, 2022, it was listed on the Sci - tech Innovation Board of the
Shanghai Stock Exchange.



Hefei Headquarters

Current Staff
190+人

R&D Staff
60%+

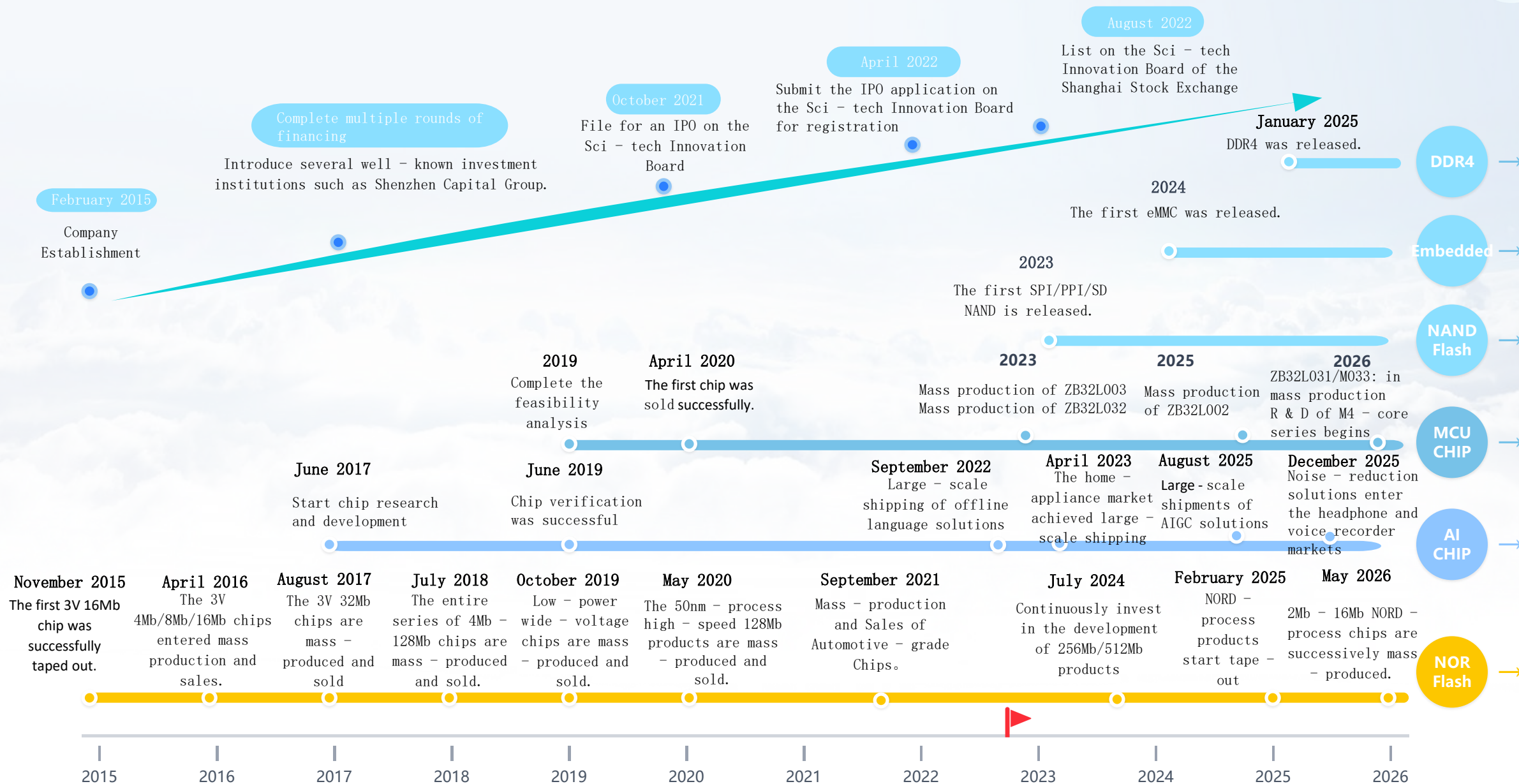
R&D & Sales
Center
Shanghai /
Hefei / Suzhou
& Shenzhen





Zbit Development History

Stock Code : 688416



 Supply chain advantages ensure the company's production capacity growth.

Stock Code: 688416



Deepen collaboration with top domestic wafer manufacturers



Since 2015, we've been strategic partners, co - developing 65nm/55nm NOR Flash products. The 50nm NOR Flash and 55nm MCU processes are industry - leading.



The world's 5th - largest and China's largest foundry, with a domestically leading chip production process platform



Huahong Semiconductor is the second-largest wafer foundry in Chinese mainland, specializing in specialty process chip manufacturing. It serves as the Company's new partner for advanced specialty processes.

Long-term stable cooperation with wafer probing and chip packaging & testing manufacturers



The company maintains stable partnerships with wafer foundries to support its long-term future growth



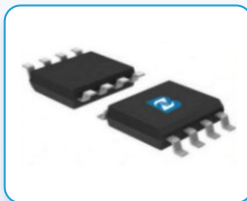
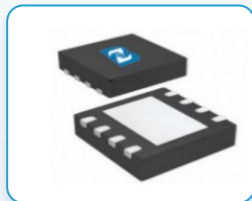
FLASH

PART 02



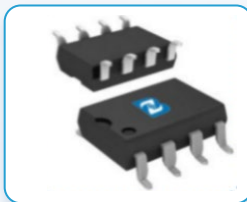
Main products: Flash memory chips

Stock Code: 688416



Full NOR Flash series: 3V high voltage, 1.2V/1.8V low voltage, 1.65 - 3.6V wide voltage

High performance, low power consumption, leading power efficiency in the industry



State-of-the-art process: NOR Flash available in 50nm

Full NOR Flash capacity range: 1Mb - 512Mb

Products supplied to renowned clients including Xiaomi, 360 and other enterprises.



Application Fields



智能手表



健身手环



电视机



路由器



智能电表



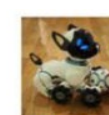
网络摄像头



TWS 耳机



机顶盒



智能玩具



行车记录仪



蓝牙音箱



手机



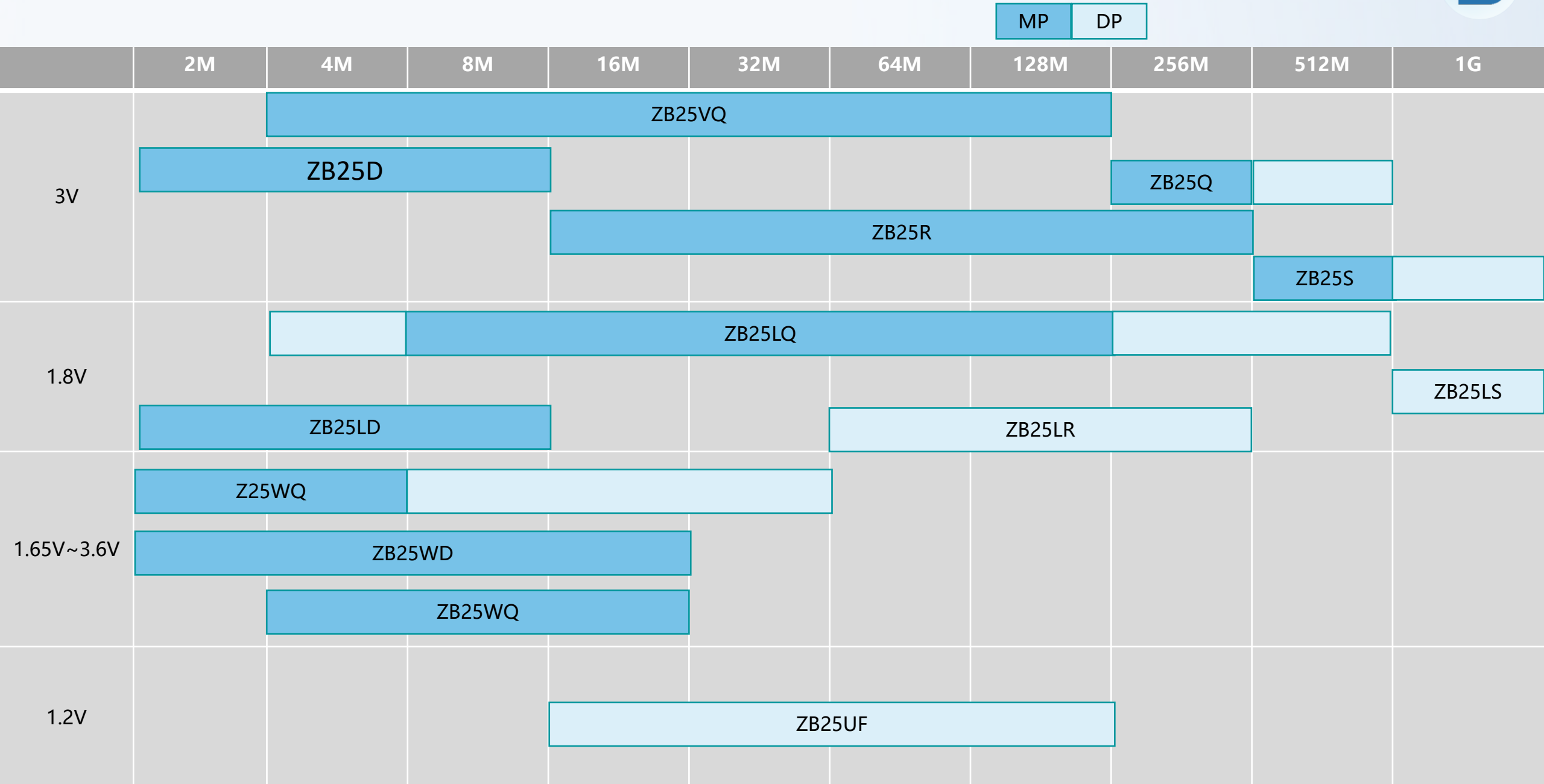
电脑



POS 机



家电





Vol	Cap	PN	Dual	Quad	QPI	DTR	SOP8 150mil	SOP8 208mil	VSOP8 208mil	TSSOP8 173mil	SOP16 300mil	DFN 6 1.0*0.72mm	DFN 6 1.2*1.2mm	DFN 8 1.5*1.5mm	DFN 8 2*3mm	DFN 8 4*3mm	DFN 8 4*4mm	DFN 8 5*6mm	DFN 8 6*8mm	TFBGA- 24 BALL	KGD
3.0V	2Mb	Z25Q20A	√	√			•	•	•	•		•	•	•	•	•	•	•	•	•	√
		ZB25D20A	√				•	•	•	•		•	•	•	•	•	•	•	•	•	√
	4Mb	ZB25Q40A	√	√			•	•	•	•			•		•	•	•	•	•	•	√
		Z25Q40A	√	√			•	•	•	•			•		•	•	•	•	•	•	√
		ZB25D40B	√				•	•	•	•			•		•	•	•	•	•	•	√
	8Mb	ZB25D80B	√				•	•	•	•						•	•	•	•	•	√
		ZB25D80C	√				•	•	•	•						•	•	•	•	•	√
	16Mb	ZB25Q16A	√	√			•	•	•	•						•	•	•	•	•	√
	256Mb	ZB25Q256	√	√	√	√		•			•							•	•	•	√
	512Mb	ZB25S512	√	√	√	√					•							•	•	•	√
2.3~ 3.6V	4Mb	Z25VQ40A	√	√			•	•	•	•			•		•	•	•	•	•	•	√
		ZB25VQ40B	√	√			•	•	•	•						•	•	•	•	•	√
	8Mb	ZB25VQ80B	√	√			•	•	•	•						•	•	•	•	•	√
	16Mb	ZB25VQ16A	√	√			•	•	•	•						•	•	•	•	•	√
	32Mb	ZB25VQ32D	√	√	√	√	•	•	•							•	•	•	•	•	√
		ZB25VQ32E	√	√	√	√	•	•	•							•	•	•	•	•	√
	64Mb	ZB25VQ64C	√	√	√	√	•	•	•								•	•	•	•	√
		ZB25VQ64D	√	√	√		•	•			•						•	•		•	√
	128Mb	ZB25VQ128E	√	√	√	√	•	•	•								•	•	•	•	√
		ZB25VQ128D	√	√	√	√		•	•									•	•	•	√
1.8V	2Mb	ZB25LD20A	√				•	•	•	•		•		•	•	•	•	•	•	•	√
	4Mb	ZB25LD40B	√				•	•	•	•					•	•	•	•	•	•	√
	8Mb	ZB25LD80C	√				•	•	•	•						•	•	•	•	•	√
		ZB25LD80B	√				•	•	•	•						•	•	•	•	•	√
	16Mb	ZB25LQ16B	√	√	√			•								•		•	•	•	√
	32Mb	ZB25LQ32B	√	√	√	√	•	•	•	•							•	•	•	•	√
	64Mb	ZB25LQ64A	√	√	√	√	•	•	•								•	•	•	•	√
	128Mb	ZB25LQ128C	√	√	√	√		•	•									•	•	•	√
1.6~ 3.6V	2Mb	Z25WQ20A	√	√			•	•	•	•		•	•		•	•	•	•	•	•	√
		ZB25WD20	√				•	•	•	•		•		•	•	•	•	•	•	•	√
	4Mb	Z25WQ40A	√	√			•	•	•	•			•		•	•	•	•	•	•	√
		ZB25WQ40A	√	√			•	•	•	•					•	•	•	•	•	•	√
		ZB25WD40C	√				•	•		•				•	•						√
	8Mb	ZB25WQ80A	√	√			•	•	•	•						•	•	•	•	•	√
		ZB25WD80C	√				•	•		•				•	•						√
	16Mb	ZB25WQ16B	√	√			•	•	•	•						•	•	•	•	•	√

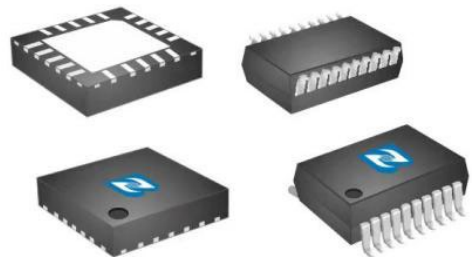


Company Product

-- MCU

PART 03





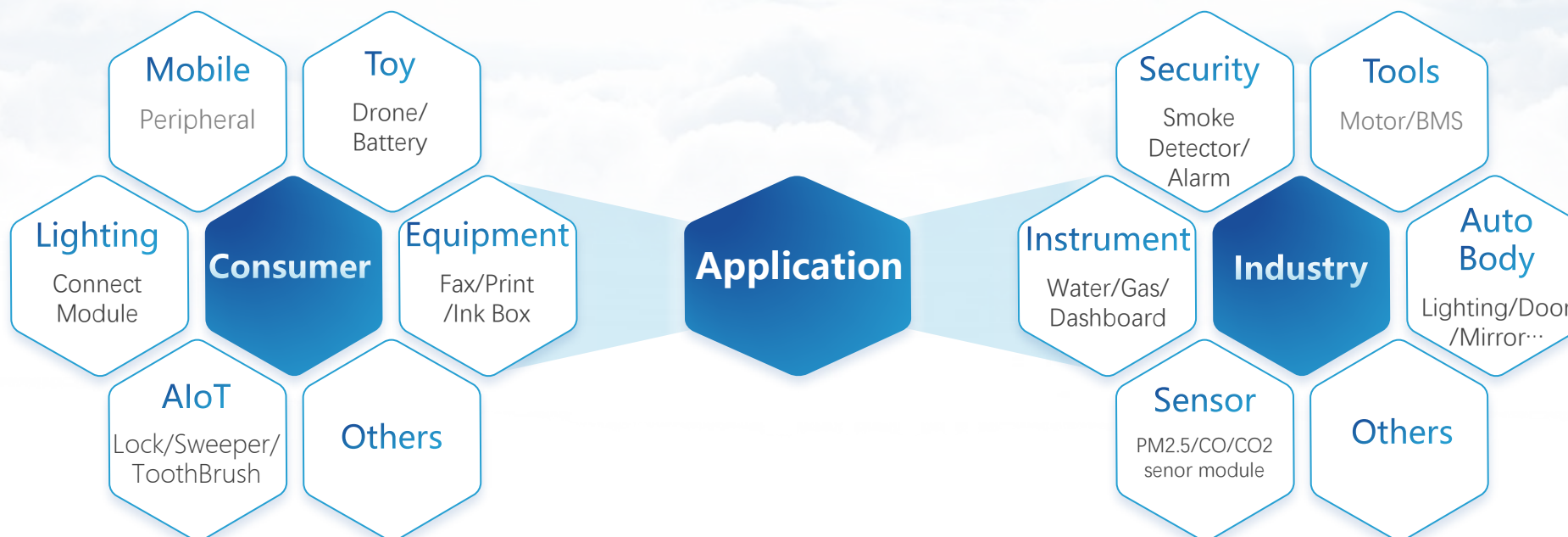
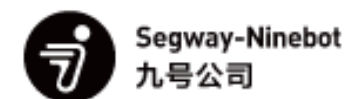
High cost performance

Low-power

55nm process

High reliability

Well-known customer list for ZBIT MCU products





- MCU design with high performance ARM Cortex-M core, Ultra low power consumption feature, with high performance Timer, include UART, IIC, SPI digital Interface and ADC, OPA, VC analog interface etc.
- Cooperation with the best IP partners such as ARM/IBM/SST etc. ensure the high quality and reliability for MCU products



- *Low power, High performance, Low cost*
- *Standard cell library, I/O, complier*

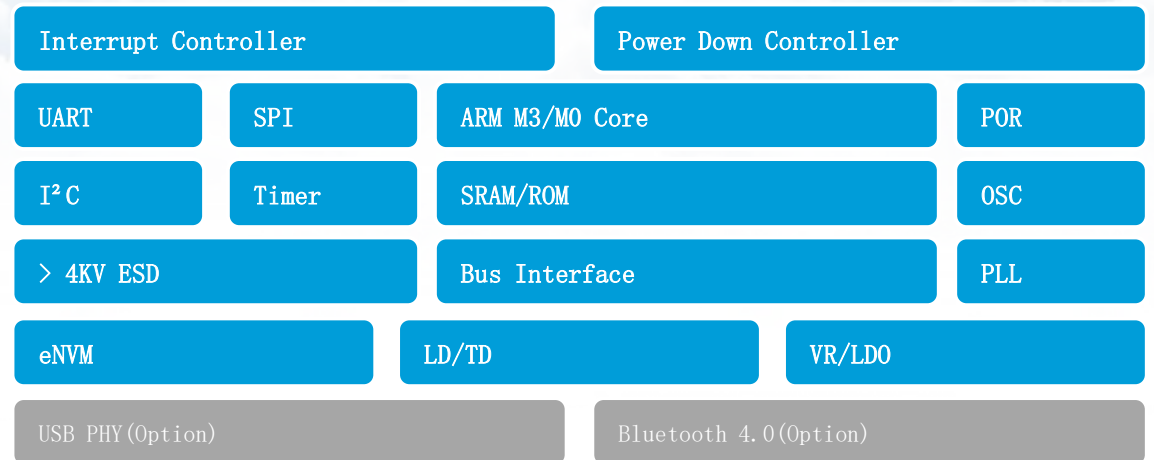


- *65nm RF*
- *45nm&65nm Low power*



- *High reliability, Safety*
- *e-Flash*

MCU IP Platform





恒烁股份
Zbit Semi, Inc.

ARM® Cortex® -M0+
ZB32 Series 32-Bit MCU Selection Table

型号	主频 MHz	Flash	SRAM	DMA	I/O	定时器								通讯								模拟				TRNG	AES	内部 温度 传感器	硬件 除法器	封装
						Ad Timer	C Timer	B Timer	LP Timer	AWK Timer	PCA	RTC	I+W WDC	UART	USART	LPUART	IIC	IIS	SPI	QSPI	One WIRE	12bit ADC	LVD	VC	OPA					
ZB32L002F5P6	24	24K	3K	-	17	1	1	2	1	1	1	1	2	2	-	1	1	-	1	-	1	7ch	1	1	-	-	-	-	-	TSSOP20
ZB32L002F5Q6	24	24K	3K	-	17	1	1	2	1	1	1	1	2	2	-	1	1	-	1	-	1	7ch	1	1	-	-	-	-	-	QFN20 (3x3)
ZB32L003F8P6	24	64K	4K	-	17	1	1	2	1	1	1	1	2	2	-	1	1	-	1	-	1	7ch	1	1	-	-	-	-	-	TSSOP20
ZB32L003F8Q6	24	64K	4K	-	17	1	1	2	1	1	1	1	2	2	-	1	1	-	1	-	1	7ch	1	1	-	-	-	-	-	QFN20 (3x3)
ZB32L032G8P6	64	64K	16K	16ch	22	3	4	2	1	1	1	1	2	2	2	-	2	1	1	1	1	11ch	1	2	-	1	1	1	-	TSSOP28
ZB32L032K8x6	64	64K	16K	16ch	25	3	4	2	1	1	1	1	2	2	1	1	2	1	2	1	-	12ch	1	2	2	1	1	1	-	LQFP32 QFN32 (5x5)
ZB32L032C8T6	64	64K	16K	16ch	39	3	4	2	1	1	1	1	2	2	2	1	2	1	2	1	1	17ch	1	2	2	1	1	1	-	LQFP48
ZB32M022E6S7	60	32K	4K	2ch	22	1	1	3	-	-	-	-	1	-	1	-	-	-	-	-	-	11ch	-	2	2	-	-	1	1	SSOP24
ZB32M022G6P7	60	32K	4K	2ch	26	1	1	3	-	-	-	-	1	-	1	-	-	-	-	-	-	11ch	-	2	2	-	-	1	1	TSSOP28

x: T: LQFP Package, Q: QFN Package



M3	Low Power	ZB32L103 (M3) 72M、128KB/32KB CAN、USB 32/48/64 PIN (Tape-out)	ZB32F103 (M3) 96M、256KB/48KB CAN、USB 48/64/100 PIN (Tape-out)	
M0	Mainstream Model	CX32L003 24M 、64KB/4KB RTC、20 PIN	ZB32L030 24M 、64KB/8KB OPA、28/32/48 PIN	ZB32L032 64M 、64KB/16KB DMA、DAC、OPA 28/32/48 PIN
	Value Model	ZB32L003 24M 、64KB/4KB RTC、20 PIN	ZB32L002 1.8V 48M 32K/4K 运放、20PIN (Kicking off)	ZB32L031 48M 、64KB/16KB (Under Feasibility Study)



Company Product

-- High-density memory

PART 04





Product	Configuration	2025				2026			
		Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
SPI NAND	3.3V SLC (x1, x2, x4) WS0N8x6 Internal ECC, 2KB/4KB Page	1 & 2 & 4Gb							
		1~4Gb, 1.8V							
SD NAND	3.3V SLC/MLC LGA8x6, SD 2.0 Internal ECC, 2KB/4KB Page	1 & 2 & 4Gb							
		32Gb							
PPI NAND	3.3V SLC 25ns BGA63/BGA24/TSOP48 8b/528B ECC, 2KB Page	2Gb							

 Planning

 CS QS



Product	Configuration	2025				2026			
		Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
eMMC	eMMC5.1 , BGA153 VCC 3.3V, VCCQ 1.8V SDR/DDR/HS200/HS400	8/32/64/128 GB							
									4GB
UFS	UFS2.2 , BGA153 VCC 3.3V, VCCQ2 1.8V M-PHY 3.0, UniPro 1.6								64~256GB
	UFS3.1 , BGA153 VCC 2.5V, VCCQ 1.2V M-PHY 4.1, UniPro 1.8								128~512GB



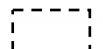
Planning



CS QS



Type	Density	Configuration	2025				2026			
			Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
DDR4	4Gb	1.2V x8/ x16 0~95°C/-40~95°C 3200/2666/2400Mbps								
	8Gb	1.2V x8/ x16 0~95°C/-40~95°C 3200/2666/2400Mbps	 							
LPDDR4x	8Gb	1.1V x32 0~95°C/-40~95°C 4266Mbps								


Planning

 CS  QS

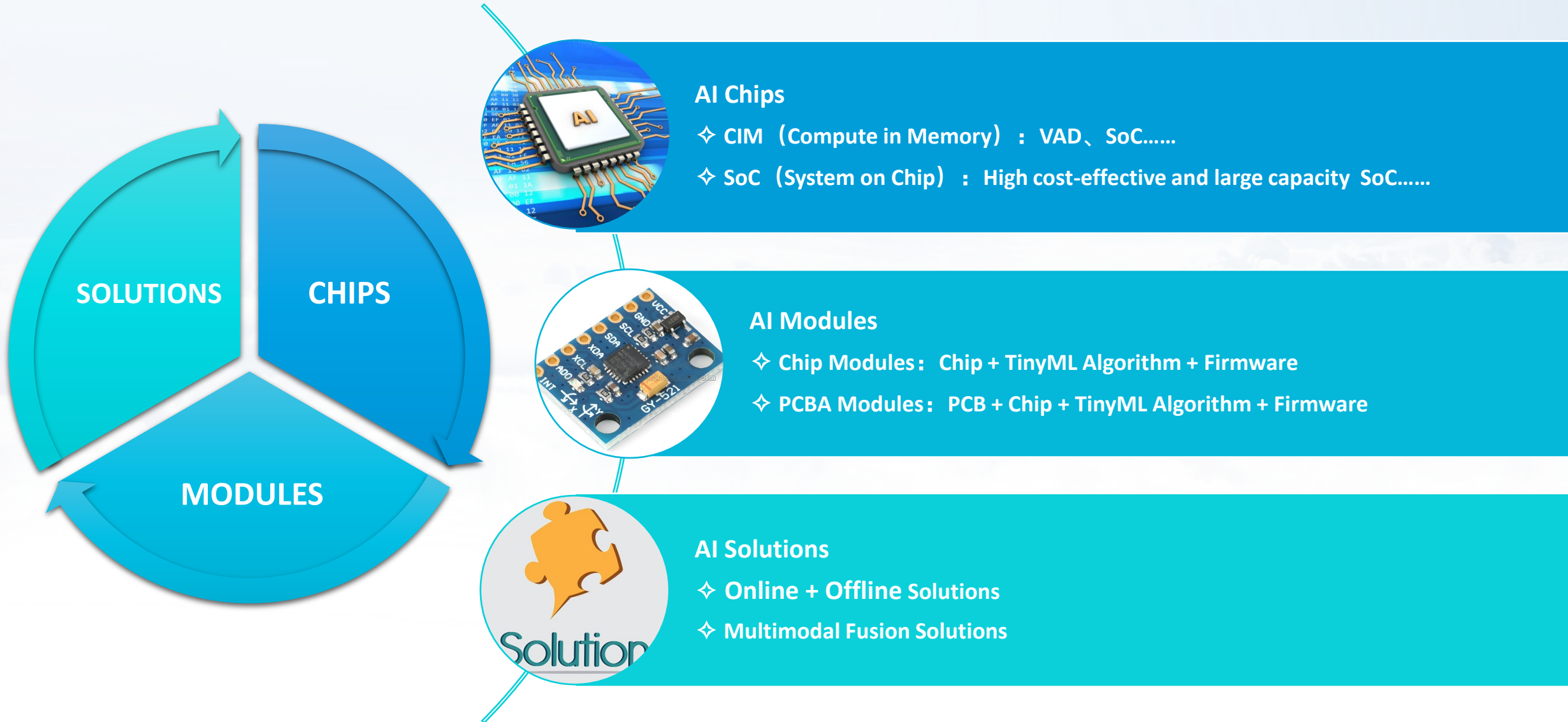


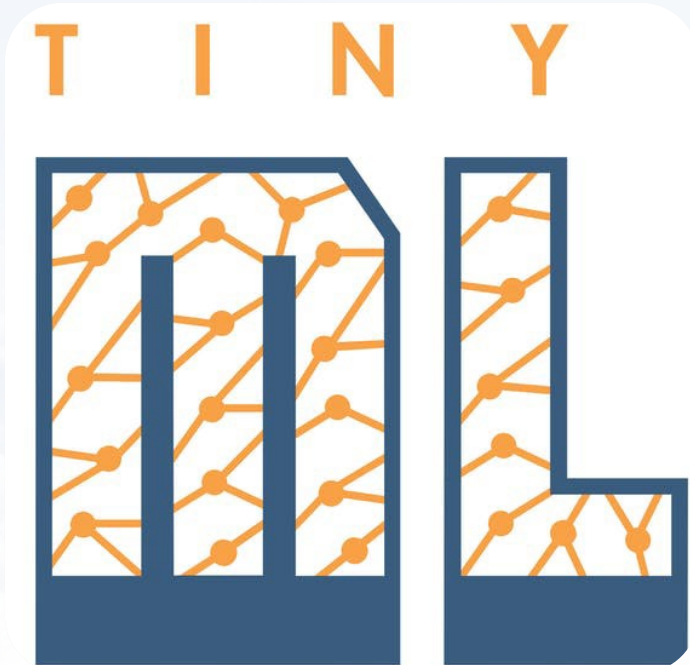
Company Product

-- AI

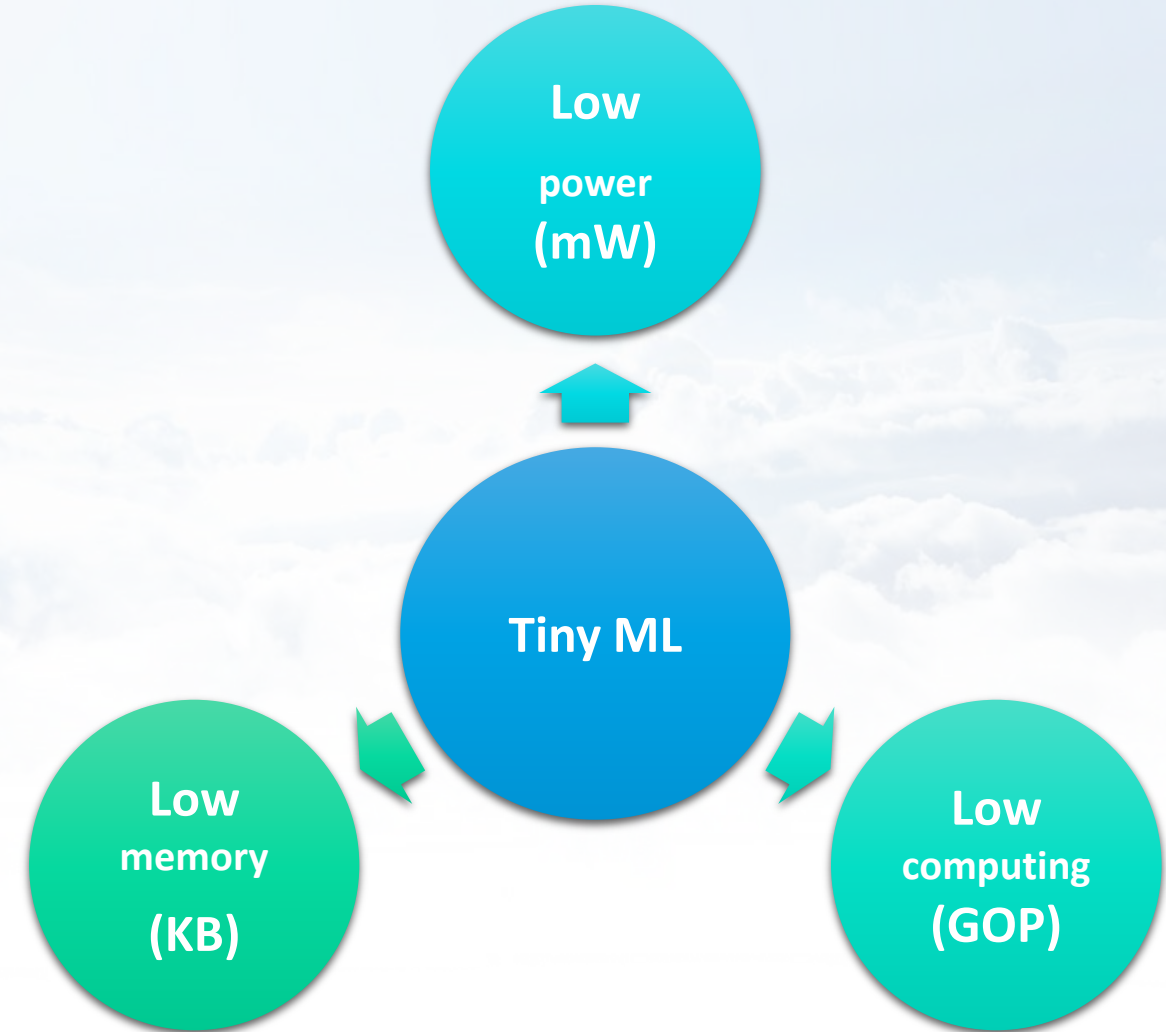
PART 05

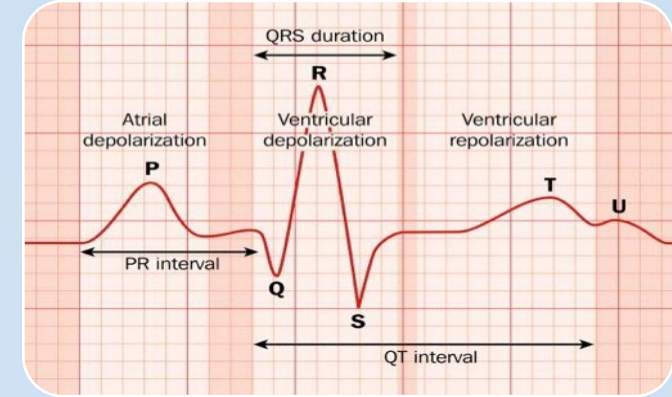
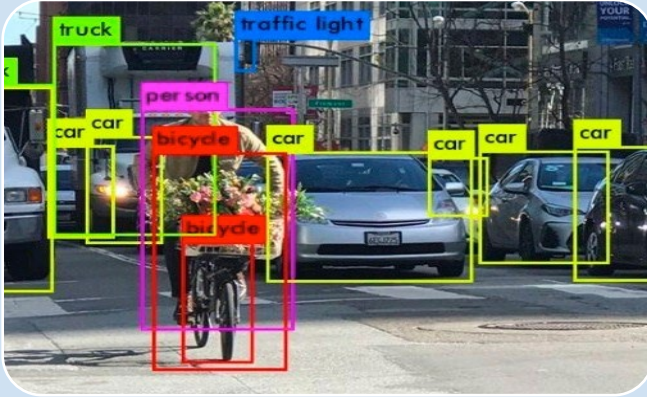






TinyML is the way, tools and technology to implement machine learning on the mW-level power consumer devices.





ZBIT-IV (Intelligent Vision)

- Visual Wake Words
 - (Model: 300K~500K params)
- Object Classification
 - (Model: 0.5~1M params)
- Object Detection
 - (Model: 0.8~2M params)

ZBIT-IA (Intelligent Audio)

- Keywords Spotting
 - (Model: 2~4K params)
- Digital Noise Reduction
 - (Model: 0.3~1M params)
- Speaker-ID
 - (Model: 0.5~2M params)

ZBIT-IT (Intelligent Time-series)

- Time-series Analysis
 - (Model: 300~700K params)
- Anomaly Time-series
 - (Model: 0.8~2M params)



ARM[®]

ARM

- Cortex-M
- Cortex-A
-



RISC-V

RISC-V

- RISC-V
- RISC



MIPS
TECHNOLOGIES

MIPS



DSP

DSP

- HiFi
- Synopsys
- ARC



TinyML
AI Audio Product and Technology

VAD
-Voice Active
Detection

KWS
-Key Word
Spotting

DNR
-Deep Noise
Reduction

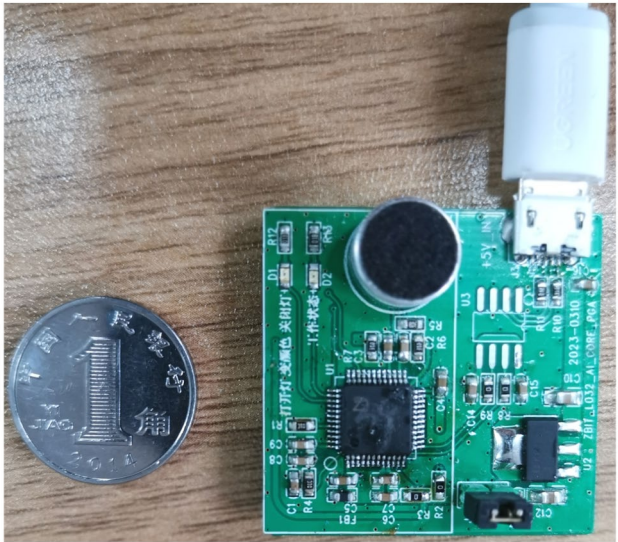
SID
-Speaker ID

AIGC
-Artificial
Intelligence
Generated
Content

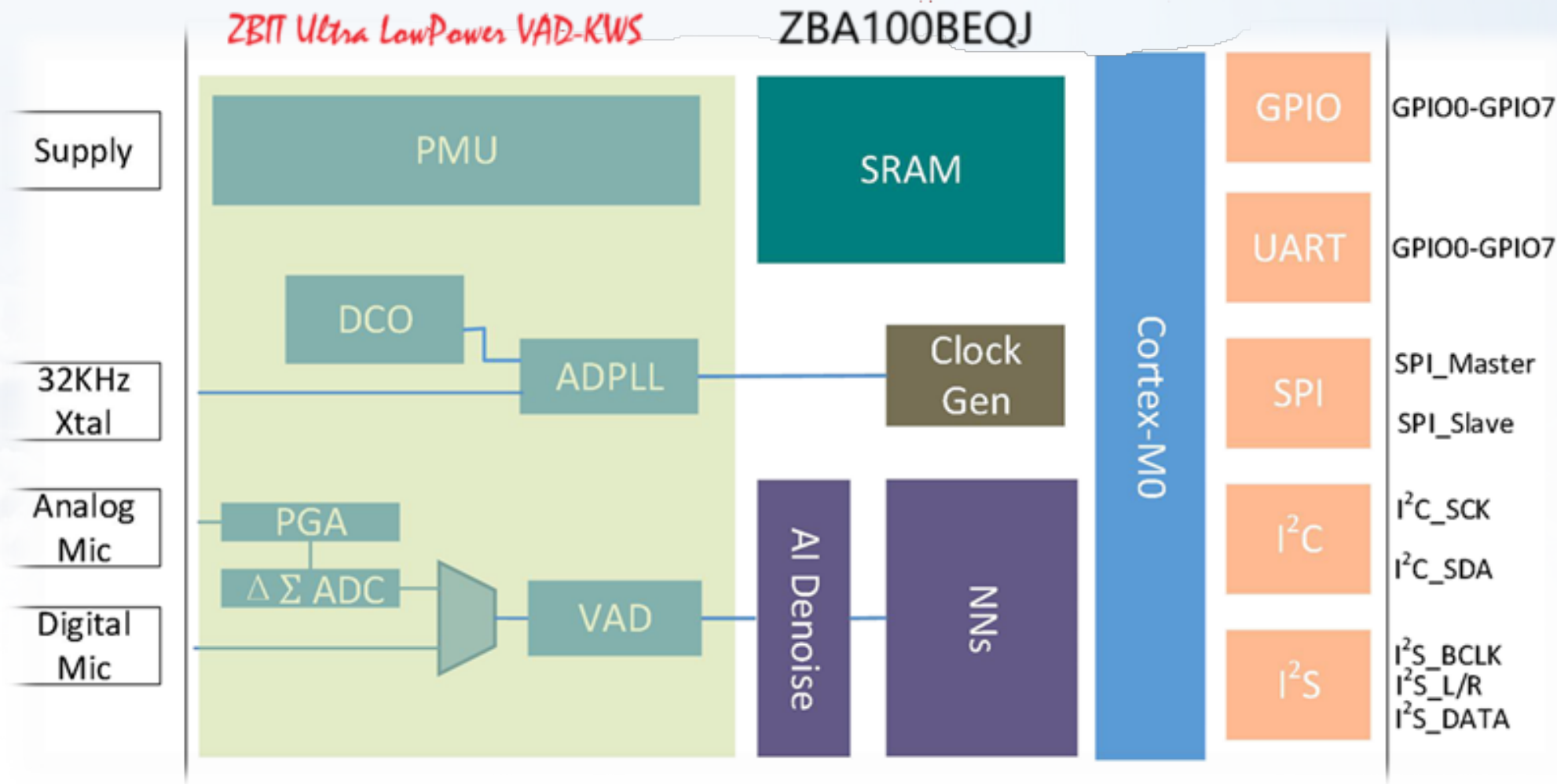
CHIP
-Ultra LowPower
Audio Chips



Name	Function	Hardware
KWS	Offline voice wakeup and recognition	M0+ 16KB+ SRAM,64KB+ FLASH, 50MHz+
DNR	Deep Noise reduction	M4 320KB+ SRAM,1MB+ FLASH, 216MHz+
Baby Crying	Baby cry detection	M0+ 16KB+ SRAM,64KB+ FLASH, 50MHz+
Glass Breaking	Glass break detection	M0+ 32KB+ SRAM,256KB+ FLASH, 100MHz+
SPEAKER ID	Voiceprint identification	RISC 32KB+ SRAM,256KB+ FLASH, 160MHz+
AEC	Acoustic Echo Cancellation	M4 324KB+ SRAM,2MB+ FLASH, 180MHz+
MSS	Music Source Separation	M7 1MB+ SRAM,2MB+ FLASH, 480MHz+



Name	Function	Hardware
KWS Module	Offline voice wakeup and KWS	M0+ (64MHz, 64KB Flash, 16KB SRAM)
Baby Crying Module	Baby cry detection	M0+ (64MHz, 64KB Flash, 16KB SRAM)
Glass Breaking Module	Glass break detection	M4+ (216MHz, 1MB Flash, 320KB SRAM)
SPEAK ID Module	Voiceprint identification	RISC (160MHz, 256KB Flash, 30KB SRAM)
Smart Fan	BLDC FOC control, Offline voice control	M3 (160MHz, 256KB Flash, 64KB SRAM)



VAD-Standby: 150uA; KWS-Active: 330uA



THANK YOU

恒久发展 烁动我芯

Sustainable Growth, Spark Our Core